Dual Buffer

The NL27WZ16 is a high performance dual buffer operating from a 1.65 to 5.5 V supply. At V_{CC} = 3 V, high impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance.

Features

- Extremely High Speed: t_{PD} 2.0 ns (typical) at $V_{CC} = 5 \text{ V}$
- Designed for 1.65 V to 5.5 V V_{CC} Operation
- Over Voltage Tolerant Inputs
- LVTTL Compatible Interface Capability With 5 V TTL Logic with V_{CC} = 3 V
- LVCMOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current Substantially Reduces System Power Requirements
- Chip Complexity: FET = 72; Equivalent Gate = 18
- These Devices are Pb-Free and are RoHS Compliant
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable

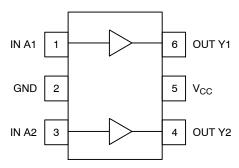


Figure 1. Pinout (Top View)

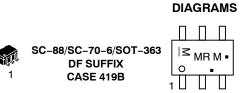


Figure 2. Logic Symbol

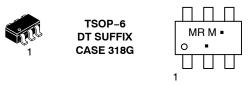


ON Semiconductor®

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MARKING



MR = Device Code
M = Date Code*

= Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

PIN ASSIGNMENT

Pin	Function	
1	IN A1	
2	GND	
3	IN A2	
4	OUT Y2	
5	V _{CC}	
6	OUT Y1	

FUNCTION TABLE

A Input	▼ Output
L	L
Н	Н

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MAXIMUM RATINGS

Symbol	Characteristics	Value	Units
V _{CC}	DC Supply Voltage	-0.5 to +7.0	V
VI	DC Input Voltage	$-0.5 \le V_{I} \le +7.0$	V
Vo	DC Output Voltage Output in Z or LOW State (Note 1)	$-0.5 \le V_0 \le +7.0$	٧
I _{IK}	DC Input Diode Current V _I < GND	-50	mA
Іок	DC Output Diode Current Vo < GND	-50	mA
lo	DC Output Sink Current	±50	mA
I _{CC}	DC Supply Current per Supply Pin	±100	mA
I _{GND}	DC Ground Current per Ground Pin	±100	mA
T _{STG}	Storage Temperature Range	-65 to +150	°C
P _D	Power Dissipation in Still Air SC-88, TSOP-6	200	mW
$\theta_{\sf JA}$	Thermal Resistance SC-88, TSOP-6	333	°C/W
TL	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
TJ	Junction Temperature Under Bias	+150	°C
V _{ESD}	ESD Withstand Voltage Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	> 2000 > 200 N/A	V
I _{Latchup}	Latchup Performance Above V _{CC} and Below GND at 85°C (Note 5)	±500	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Io absolute maximum rating must be observed.

2. Tested to EIA/JESD22-A114-A

3. Tested to EIA/JESD22-A115-A

- Tested to JESD22-C101-A
 Tested to EIA/JESD78

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Units
V _{CC}	Supply Voltage Operating Data Retention Only	1.65 1.5	5.5 5.5	V
VI	Input Voltage	0	5.5	V
Vo	Output Voltage (High or LOW State)	0	5.5	V
T _A	Operating Free-Air Temperature	-55	+125	°C
Δt/ΔV	Input Transition Rise or Fall Rate V _{CC} = 1.8 V ±0.15 V V _{CC} = 2.5 V ±0.2 V V _{CC} = 3.0 V ±0.3 V V _{CC} = 5.0 V ±0.5 V	0 0 0	20 20 10 5	ns/V

DC ELECTRICAL CHARACTERISTICS

			V _{CC} T _A	$T_A = 25^{\circ}C$		-55°C ≤ T	T _A ≤ 125°C		
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Units
V _{IH}	High-Level Input Voltage		1.65 to 1.95 2.3 to 5.5	0.75 V _{CC} 0.7 V _{CC}			0.75 V _{CC} 0.7 V _{CC}		V
V _{IL}	Low-Level Input Voltage		1.65 to 1.95 2.3 to 5.5			0.25 V _{CC} 0.3 V _{CC}		0.25 V _{CC} 0.3 V _{CC}	V
V _{OH}	High-Level Output Voltage V _{IN} = V _{IH}	I _{OH} = -100 μA	1.65 1.8 2.3 3.0 4.5	1.55 1.7 2.2 2.9 4.4	1.65 1.8 2.3 3.0 4.5		1.55 1.7 2.2 2.9 4.4		V
		I _{OH} = -4 mA I _{OH} = -8 mA I _{OH} = -16 mA I _{OH} = -24 mA I _{OH} = -32 mA	1.65 2.3 3.0 3.0 4.5	1.29 1.9 2.4 2.3 3.8	1.52 2.15 2.80 2.68 4.20		1.29 1.9 2.4 2.3 3.8		V
V _{OL}	Low-Level Output Voltage V _{IN} = V _{IL}	Ι _{ΟL} = 100 μΑ	1.65 1.8 2.3 3.0 4.5		0.0 0.0 0.0 0.0 0.0	0.1 0.1 0.1 0.1 0.1		0.1 0.1 0.1 0.1 0.1	V
		I _{OL} = 4 mA I _{OL} = 8 mA I _{OL} = 16 mA I _{OL} = 24 mA I _{OL} = 32 mA	1.65 2.3 3.0 3.0 4.5		0.08 0.10 0.15 0.22 0.22	0.24 0.30 0.40 0.55 0.55		0.24 0.30 0.40 0.55 0.55	V
I _{IN}	Input Leakage Current	V _{IN} = 5.5 V or GND	0 to 5.5			±0.1		±1.0	μΑ
I _{OFF}	Power Off Leakage Current	V _{IN} = 5.5 V or V _{OUT} = 5.5 V	0			1		10	μΑ
I _{CC}	Quiescent Supply Current	V _{IN} = 5.5 V or GND	5.5			1		10	μА

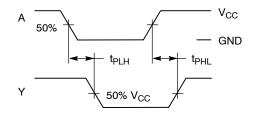
AC ELECTRICAL CHARACTERISTICS t_R = t_F = 2.5 ns; C_L = 50 pF; R_L = 500 Ω

				T _A = 25°C		-55°C ≤ T _A ≤ 125°C			
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Min	Max	Units
t _{PLH}	Propagation Delay	$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	1.8 ± 0.15	1.8	8.0	9.6	1.8	10.2	ns
^Į PHL	t _{PHL} (Figure 3 and 4)	$R_L = 1 M\Omega$, $C_L = 15 pF$	2.5 ± 0.2	1.0	3.0	5.2	1.0	5.8	
		$R_L = 1 \text{ M}\Omega$, $C_L = 15 \text{ pF}$	00.00	0.8	2.3	3.6	0.8	4.0	
		$R_L = 500 \ \Omega, C_L = 50 \ pF$	3.3 ± 0.3	1.2	3.0	4.6	1.2	5.1	
		R_L = 1 M Ω , C_L = 15 pF	50105	0.5	1.8	2.9	0.5	3.2	
		$R_L = 500 \ \Omega, C_L = 50 \ pF$	5.0 ± 0.5	0.8	2.4	3.8	0.8	4.2	

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	ter Condition		Units
C _{IN}	Input Capacitance	V_{CC} = 5.5 V, V_I = 0 V or V_{CC}	7.0	pF
C _{PD}	Power Dissipation Capacitance (Note 6)	10 MHz, V_{CC} = 3.3 V, V_{I} = 0 V or V_{CC} 10 MHz, V_{CC} = 5.5 V, V_{I} = 0 V or V_{CC}	9 11	pF

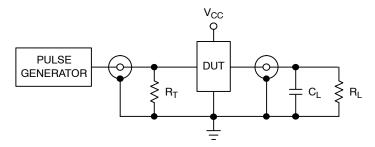
^{6.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \cdot V_{CC} \cdot f_{in} + I_{CC}$. C_{PD} is used to determine the no–load dynamic power consumption; $P_D = C_{PD} \cdot V_{CC}^2 \cdot f_{in} + I_{CC} \cdot V_{CC}$.



PROPAGATION DELAYS

 $t_R = t_F = 2.5 \text{ ns}, 10\% \text{ to } 90\%; f = 1 \text{ MHz}; t_W = 500 \text{ ns}$

Figure 3. Switching Waveforms



 $R_T = Z_{OUT}$ of pulse generator (typically 50 Ω)

Figure 4. Test Circuit

ORDERING INFORMATION

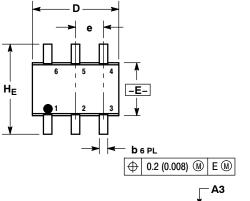
Device	Package	Shipping [†]
NL27WZ16DFT2G	SC-88/SC-70/SOT-363 (Pb-Free)	3000 /Tape & Reel
NLV27WZ16DFT2G*	SC-88/SC-70/SOT-363 (Pb-Free)	3000 /Tape & Reel
NL27WZ16DTT1G	TSOP-6 (Pb-Free)	3000 /Tape & Reel

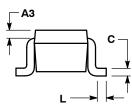
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

PACKAGE DIMENSIONS

SC-88/SC70-6/SOT-363 CASE 419B-02 **ISSUE W**

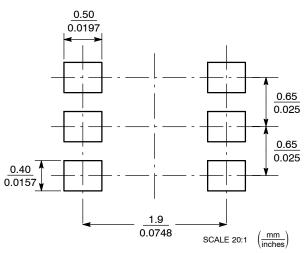




- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. 419B-01 OBSOLETE, NEW STANDARD 419B-02.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.80	0.95	1.10	0.031	0.037	0.043	
A1	0.00	0.05	0.10	0.000	0.002	0.004	
A3		0.20 RE	ΕF	0.008 REF			
b	0.10	0.21	0.30	0.004	0.008	0.012	
С	0.10	0.14	0.25	0.004	0.005	0.010	
D	1.80	2.00	2.20	0.070	0.078	0.086	
Е	1.15	1.25	1.35	0.045	0.049	0.053	
е		0.65 BS	С	0	.026 BS	С	
L	0.10	0.20	0.30	0.004	0.008	0.012	
HE	2.00	2.10	2.20	0.078	0.082	0.086	

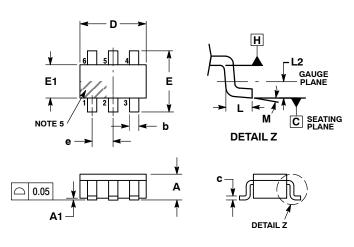
SOLDERING FOOTPRINT*



^{*}For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

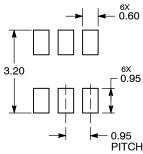
TSOP-6 CASE 318G-02 **ISSUE U**



- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
- GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSIONS D AND E1 ARE DETERMINED AT DATUM H. PIN ONE INDICATOR MUST BE LOCATED IN THE INDICATED ZONE.

	MILLIMETERS					
DIM	MIN	NOM	MAX			
Α	0.90	1.00	1.10			
A1	0.01	0.06	0.10			
b	0.25	0.38	0.50			
С	0.10	0.18	0.26			
D	2.90	3.00	3.10			
E	2.50	2.75	3.00			
E1	1.30	1.50	1.70			
е	0.85	0.95	1.05			
L	0.20	0.40	0.60			
L2	0.25 BSC					
M	0°					

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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